

# SN54F374, SN74F374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

SDFS077A – D2932, MARCH 1987 – REVISED OCTOBER 1993

- Eight D-Type Flip-Flops in a Single Package
- 3-State Bus-Driving True Outputs
- Full Parallel Access for Loading
- Buffered Control Inputs
- Package Options Include Plastic Small-Outline (SOIC) and Shrink Small-Outline (SSOP) Packages, Ceramic Chip Carriers, and Plastic and Ceramic DIPs

## description

These 8-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight flip-flops of the 'F374 are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels that were set up at the data (D) inputs.

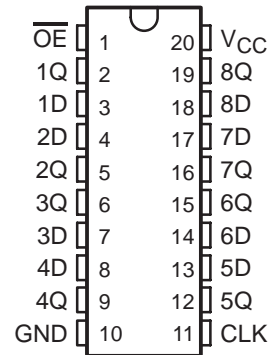
A buffered output enable ( $\overline{OE}$ ) input can be used to place the eight outputs in either a normal logic state (high or low) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

The output enable ( $\overline{OE}$ ) input does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

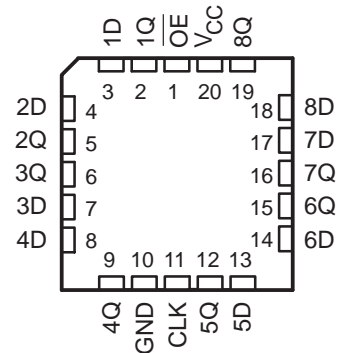
The SN74F374 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54F374 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74F374 is characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

SN54F374 . . . J PACKAGE  
SN74F374 . . . DB, DW, OR N PACKAGE  
(TOP VIEW)



SN54F374 . . . FK PACKAGE  
(TOP VIEW)



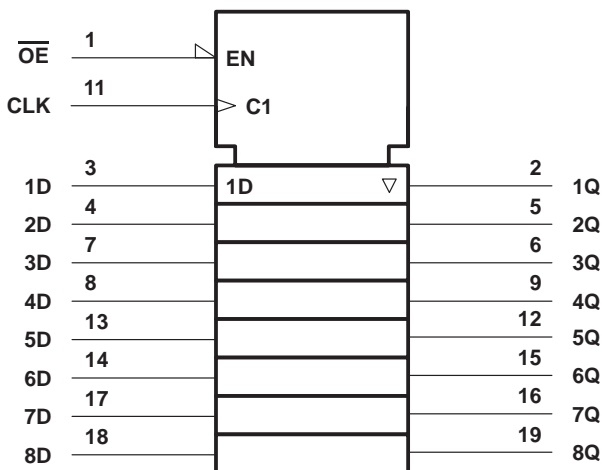
FUNCTION TABLE  
(each flip-flop)

INPUTS			OUTPUT
$\overline{OE}$	CLK	D	Q
L	$\uparrow$	H	H
L	$\uparrow$	L	L
L	H or L	X	$Q_0$
H	X	X	Z

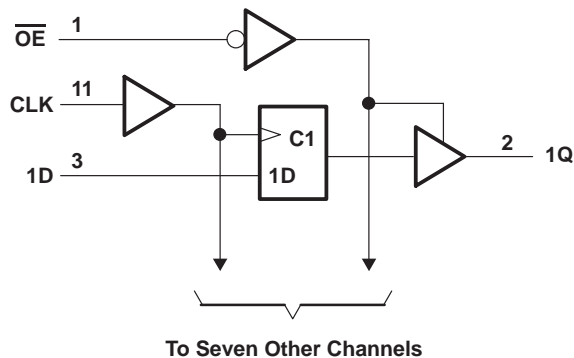
# SN54F374, SN74F374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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## logic symbol†



## logic diagram (positive logic)



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	-1.2 V to 7 V
Input current range .....	-30 mA to 5 mA
Voltage range applied to any output in the disabled or power-off state .....	-0.5 V to 5.5 V
Voltage range applied to any output in the high state .....	-0.5 V to $V_{CC}$
Current into any output in the low state: SN54F374 .....	40 mA
SN74F374 .....	48 mA
Operating free-air temperature range: SN54F374 .....	-55°C to 125°C
SN74F374 .....	0°C to 70°C
Storage temperature range .....	-65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

## recommended operating conditions

	SN54F374			SN74F374			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$ Supply voltage	4.5	5	5.5	4.5	5	5.5	V
$V_{IH}$ High-level input voltage	2			2			V
$V_{IL}$ Low-level input voltage			0.8			0.8	V
$I_{IK}$ Input clamp current			-18			-18	mA
$I_{OH}$ High-level output current			-3			-3	mA
$I_{OL}$ Low-level output current			20			24	mA
$T_A$ Operating free-air temperature	-55		125	0		70	°C

# SN54F374, SN74F374 OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		SN54F374			SN74F374			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
$V_{IK}$	$V_{CC} = 4.5\text{ V}$ ,	$I_I = -18\text{ mA}$			-1.2			-1.2	V
$V_{OH}$	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -1\text{ mA}$	2.5	3.4		2.5	3.4		V
		$I_{OH} = -3\text{ mA}$	2.4	3.3		2.4	3.3		
$V_{OL}$	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 20\text{ mA}$		0.3	0.5				V
		$I_{OL} = 24\text{ mA}$				0.35	0.5		
$I_{OZH}$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 2.7\text{ V}$			50			50	$\mu\text{A}$
$I_{OZL}$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 0.5\text{ V}$			-50			-50	$\mu\text{A}$
$I_I$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 7\text{ V}$			0.1			0.1	mA
$I_{IH}$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 2.7\text{ V}$			20			20	$\mu\text{A}$
$I_{IL}$	$V_{CC} = 5.5\text{ V}$ ,	$V_I = 0.5\text{ V}$			-0.6			-0.6	mA
$I_{OS}^\ddagger$	$V_{CC} = 5.5\text{ V}$ ,	$V_O = 0$	-60		-150	-60		-150	mA
$I_{CCZ}$	$V_{CC} = 5.5\text{ V}$ ,	See Note 2		55	86		55	86	mA

† All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2:  $I_{CCZ}$  is measured with  $\overline{OE}$  at 4.5 V and all other inputs grounded.

**timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)**

			$V_{CC} = 5\text{ V}$ , $T_A = 25^\circ\text{C}$		SN54F374		SN74F374		UNIT
			'F374		MIN	MAX	MIN	MAX	
			MIN	MAX					
$f_{\text{clock}}$	Clock frequency		0	100	0	60	0	70	MHz
$t_w$	Pulse duration		CLK high		7	7	7		ns
			CLK low		6	6	6		
$t_{su}$	Setup time, data before CLK↑		High		2	2.5	2		ns
			Low		2	2	2		
$t_h$	Hold time, data after CLK↑		High		2	2	2		ns
			Low		2	2.5	2		

# SN54F374, SN74F374

## OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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### switching characteristics (see Note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, C <sub>L</sub> = 50 pF, R <sub>L</sub> = 500 Ω, T <sub>A</sub> = 25°C			V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R <sub>L</sub> = 500 Ω, T <sub>A</sub> = MIN to MAX†				UNIT
			'F374			SN54F374		SN74F374		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			100			60		70		MHz
t <sub>PLH</sub>	CLK	Q	3.2	6.1	8.5	3.2	10.5	3.2	10	ns
t <sub>PHL</sub>			3.2	6.1	8.5	3.2	11	3.2	10	
t <sub>PZH</sub>	$\overline{OE}$	Q	1.2	8.6	11.5	1.2	14	1.2	12.5	ns
t <sub>PZL</sub>			1.2	5.4	7.5	1.2	10	1.2	8.5	
t <sub>PHZ</sub>	$\overline{OE}$	Q	1.2	4.9	7	1.2	8	1.2	8	ns
t <sub>PLZ</sub>			1.2	3.9	5.5	1.2	7.5	1.2	6.5	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 3: Load circuits and waveforms are shown in Section 1.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9759001Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9759001Q2A SNJ54F 374FK	<a href="#">Samples</a>
5962-9759001QRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9759001QR A SNJ54F374J	<a href="#">Samples</a>
5962-9759001QRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9759001QR A SNJ54F374J	<a href="#">Samples</a>
5962-9759001QSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9759001QS A SNJ54F374W	<a href="#">Samples</a>
5962-9759001QSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9759001QS A SNJ54F374W	<a href="#">Samples</a>
JM38510/34105B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 34105B2A	<a href="#">Samples</a>
JM38510/34105B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 34105B2A	<a href="#">Samples</a>
JM38510/34105BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 34105BRA	<a href="#">Samples</a>
JM38510/34105BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 34105BRA	<a href="#">Samples</a>
JM38510/34105BSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 34105BSA	<a href="#">Samples</a>
JM38510/34105BSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 34105BSA	<a href="#">Samples</a>
M38510/34105B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 34105B2A	<a href="#">Samples</a>
M38510/34105B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 34105B2A	<a href="#">Samples</a>
M38510/34105BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 34105BRA	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
M38510/34105BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 34105BRA	<a href="#">Samples</a>
M38510/34105BSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 34105BSA	<a href="#">Samples</a>
M38510/34105BSA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 34105BSA	<a href="#">Samples</a>
SN54F374J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54F374J	<a href="#">Samples</a>
SN54F374J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54F374J	<a href="#">Samples</a>
SN74F374DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI	0 to 70		
SN74F374DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI	0 to 70		
SN74F374DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F374	<a href="#">Samples</a>
SN74F374DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F374	<a href="#">Samples</a>
SN74F374DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F374	<a href="#">Samples</a>
SN74F374DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F374	<a href="#">Samples</a>
SN74F374DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F374	<a href="#">Samples</a>
SN74F374DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F374	<a href="#">Samples</a>
SN74F374DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F374	<a href="#">Samples</a>
SN74F374DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F374	<a href="#">Samples</a>
SN74F374DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F374	<a href="#">Samples</a>
SN74F374DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	F374	<a href="#">Samples</a>
SN74F374N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74F374N	<a href="#">Samples</a>
SN74F374N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74F374N	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74F374N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74F374N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74F374NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74F374	<a href="#">Samples</a>
SN74F374NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74F374	<a href="#">Samples</a>
SNJ54F374FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9759001Q2A SNJ54F 374FK	<a href="#">Samples</a>
SNJ54F374FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9759001Q2A SNJ54F 374FK	<a href="#">Samples</a>
SNJ54F374J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9759001QR A SNJ54F374J	<a href="#">Samples</a>
SNJ54F374J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9759001QR A SNJ54F374J	<a href="#">Samples</a>
SNJ54F374W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9759001QS A SNJ54F374W	<a href="#">Samples</a>
SNJ54F374W	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9759001QS A SNJ54F374W	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

<sup>(5)</sup> Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54F374, SN74F374 :**

● Catalog: [SN74F374](#)

● Military: [SN54F374](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

● Military - QML certified for Military and Defense Applications



## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F374DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74F374DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74F374NSR	SO	NS	20	2000	330.0	24.4	9.0	13.0	2.4	12.0	24.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F374DBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74F374DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74F374NSR	SO	NS	20	2000	367.0	367.0	45.0

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - (C) Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - (D) The 20 pin end lead shoulder width is a vendor option, either half or full width.



# DW0020A



# PACKAGE OUTLINE

## SOIC - 2.65 mm max height

SOIC



4220724/A 05/2016

**NOTES:**

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

# EXAMPLE BOARD LAYOUT

DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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